



Refining & Chemicals
Polymers

TPSeal® PE ESD06

Technical Data Sheet
ESD Specialty Compound
Rotational Moulding
Produced in Europe

Description

TPSeal® PE ESD06 is a black conductive Polyethylene-Carbon NanoTubes compound for rotomolding. The use of specific Carbon NanoTubes provides the material with an outstanding cleanliness compared to existing products. The very low Carbon Nanotubes loading preserves the excellent mechanical properties of the virgin polymer.

TPSeal® PE ESD06 is available in powder form.

Main Characteristics

- ✓ Exceptional cleanliness
- ✓ Good processability

Application

Rotomoulded objects that can be used in ATEX environment and for transport of electrostatic sensitive components.

Properties

Property	Method	Unit	Typical value (*)
Density (**)	ISO 1183	g/cm ³	0.935
Melt Flow Rate (190°C/2.16kg)	ISO 1133/D	g/10min	6.0
Surface resistance	IEC 61340-5-1	Ω	10 ⁴ – 10 ⁶

(*) Data not intended for specification purposes (**) Based on natural resin

Processing conditions

It is recommended to keep product dry prior use for production.

Handling and storage

Please refer to the material safety data sheet (MSDS) for handling and storage information. It is advisable to convert the product within one year after delivery provided storage conditions are used as given in the MSDS of our product.

MSDS may be obtained from the website: <http://www.polymers.total.com/>

Specialty Compound

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